



Material Content Data Sheet



Sales Product Name		TLE4268G		Issued		28. August 2013		
MA#		MA000835124						
Package		PG-DSO-20-35		Weight*		478.14 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.950	0.62	0.62	6170	6170
leadframe	inorganic material	phosphorus	7723-14-0	0.036	0.01		75	
	non noble metal	zinc	7440-66-6	0.143	0.03		299	
	non noble metal	iron	7439-89-6	2.862	0.60		5985	
wire	non noble metal	copper	7440-50-8	116.197	24.30	24.94	243017	249376
	noble metal	gold	7440-57-5	0.328	0.07	0.07	685	685
	encapsulation	organic material	carbon black	1333-86-4	0.700	0.15		1464
plastics	plastics	epoxy resin	-	32.209	6.74		67364	
	inorganic material	silicondioxide	60676-86-0	317.192	66.33	73.22	663386	732214
leadfinish	non noble metal	tin	7440-31-5	2.746	0.57	0.57	5743	5743
plating	noble metal	silver	7440-22-4	1.177	0.25	0.25	2461	2461
glue	plastics	epoxy resin	-	0.401	0.08		838	
	noble metal	silver	7440-22-4	1.202	0.25	0.33	2513	3351
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com